

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A mask, comprising:
a substrate in which an aperture is formed;
a mask member which, along with being formed with a plurality of through holes, is joined to said substrate in correspondence to said aperture; and
spacers which are sufficiently rigid not to deform when pressed so as to hold said substrate and said mask member with a predetermined gap between ~~them~~ them,
wherein said spacers consist of a plurality of spherical bodies having a diameter that is substantially the same as said predetermined gap.
2. (Previously Presented) A mask according to claim 1, wherein said spacers are disposed along with an adhesive in a junction region between said substrate and said mask member.
3. (Canceled)
4. (Withdrawn) A method of manufacturing a mask, comprising:
a process of preparing a substrate which is formed with an aperture, a mask member which is formed with a plurality of through holes, and spacers;
a process of mixing said spacers with an adhesive which is to join together said substrate and said mask member;
a process of applying said adhesive with said spacers mixed therein to a junction region between said substrate and said mask member; and
a process of joining said mask member to said substrate in correspondence to said aperture.

5. (Withdrawn) A method of manufacturing a mask according to claim 4, wherein said spacers are spheres which have a predetermined diameter.
6. (Withdrawn) A method of manufacturing a mask, comprising:
 - a process of preparing a substrate which is formed with an aperture, and a mask member in which a plurality of through holes are formed in an opaque element;
 - a process of applying a photo-curing adhesive to said substrate or to said mask member;
 - a process of joining said mask member to said substrate in correspondence to said aperture;
 - a process of squeezing out said photo-curing adhesive which is adhered to said substrate and said mask member from the junction region between said substrate and said mask member;
 - a process of curing a portion of said photo-curing adhesive by illuminating it with light from the side of said mask member; and
 - a process of curing said photo-curing adhesive by illuminating it with light from the side of said substrate, at least via said aperture.
7. (Withdrawn) A method of manufacturing a mask according to claim 6, wherein said substrate is made from an optically transparent material.
8. (Withdrawn) A method of manufacturing a mask according to claim 6, wherein said photo-curing adhesive is caused to leak out from the junction region between said substrate and said mask member, only at the outer peripheral side of said mask member.
9. (Withdrawn) A method of manufacturing a mask according to claim 6, comprising a process of, after having adhered together said substrate and said mask member, applying said photo-curing adhesive to the outer peripheral side of said mask member.
10. (Withdrawn) A method of manufacturing a mask, comprising:

a process of preparing a substrate which is formed with an aperture, and a mask member in which a plurality of through holes are formed;

a process of joining said mask member to said substrate in correspondence to said aperture; and

a process of managing the temperature of the junction between said mask member and said substrate.

11. (Withdrawn) A method of manufacturing a mask according to claim 10, wherein said mask is a mask in which, along with a plurality of said apertures being formed in said substrate, a plurality of said mask members are joined in respective correspondence to said apertures, and the temperature of the junction for each of said plurality of mask members is managed.

12. (Withdrawn) A method of manufacturing a mask according to claim 10, wherein said mask member and said substrate are joined together by being brought to a predetermined temperature.

13. (Withdrawn) A method of manufacturing a mask according to claim 12, wherein said predetermined temperature is the temperature of said mask during vapor deposition processing using said mask.

14. (Withdrawn) A method of manufacturing a mask, comprising:
a process of preparing a substrate which is formed with an aperture, and a mask member in which a plurality of through holes are formed in an opaque element;
a process of mixing spacers into a photo-curing adhesive which joins together said substrate and said mask member;
a process of applying said photo-curing adhesive to said substrate or to said mask member;

a process of joining said mask member to said substrate in correspondence to said aperture;

a process of squeezing out said photo-curing adhesive which is adhered to said substrate and said mask member from the junction region between said substrate and said mask member;

a preliminary curing process of curing a portion of said photo-curing adhesive by illuminating it with light from the side of said mask member; and

a main curing process of curing said photo-curing adhesive by illuminating it with light from the side of said substrate, at least via said aperture.

15. (Withdrawn) A method of manufacturing a mask according to claim 14, wherein, in at least said preliminary curing process and said main curing process, the temperature of the junction between said mask member and said substrate is managed.

16. (Withdrawn) A device for manufacturing a mask comprising a substrate which is formed with an aperture, and a mask member which, along with being formed with a plurality of through holes, is joined in correspondence to said aperture; said device comprising:

a mask support section which holds said mask member; a mask temperature management section which manages the temperature of said mask member, a substrate support section which holds said substrate; and

a substrate temperature management section which manages the temperature of said substrate;

wherein said mask support section and said substrate support section are shifted relative to one another, and said mask member is adhered to said substrate.

17. (Withdrawn) A device for manufacturing a mask according to claim 16, comprising a lamp which cures a photo-curing adhesive which is applied to the junction region of said substrate and said mask member.

18. (Withdrawn) A method of manufacturing a layer of luminescent material, wherein, as a mask which is used when forming a layer of luminescent material by vapor deposition, there is used:

a mask according to claim 1.

19-20. (Canceled)

21. (Previously Presented) A mask according to claim 2, wherein said substrate includes a transparent material.

22. (Previously Presented) A mask according to claim 2, wherein the adhesive is photo-curing.

23. (Previously Presented) A mask according to claim 2, wherein the adhesive is disposed at an outer peripheral side of said mask member.